



# Bill of Materials

TI DESIGNS

TIPD130: HV input comparator

Item	Quantity	Value	Designator	Description	Manufacturer	Manufacturer Part Number	Supplier Part Number
1	4	0.01uF	C1, C2, C3, C5	CAP, CERM, 0.01uF, 100V, +/-10%, X7R, 0805	TDK Corporation	C2012X7R2A103K085AA	445-1343-1-ND
2	1	10pF	C4	CAP, CERM, 10pF, 100V, +/-5%, C0G/NP0, 0805	Kemet	C0805C100J1GACTU	399-1109-1-ND
3	2	1uF	C6, C7	CAP, CERM, 1uF, 25V, +/-10%, X7R, 1206	AVX Corporation	12063C105KAT2A	478-1567-1-ND
4	2		J1, J5	3 contact eurostyle terminal block	TE Connectivity	282834-3	A98334-ND
5	2		J2, J4	2 contact eurostyle terminal block	TE Connectivity	282834-2	A98333-ND
6	1		J3	Header, TH, 100mil, 3x2, Gold plated, 230 mil above insulator	Samtec Inc	TSW-103-07-G-D	SAM1028-03-ND
7	2	220k	R1A, R4A	RES, 220k ohm, 0.1%, 0.125W, 0805 SMD	Panasonic Electronic Components	ERA-6AEB224V	P220KDATR-ND
8	2	6.8k	R1B, R4B	RES, 6.8k ohm, 0.1%, 0.125W, 0805 SMD	Panasonic Electronic Components	ERA-6AEB682V	P6.8KDATR-ND
9	2	49.9k	R2A, R5A	RES 49.9K OHM 1/8W .1% 0805 SMD	Panasonic Electronic Components	ERA-6AEB4992V	P49.9KDACT-ND
10	2	0.0	R2B, R5B	RES 0.0 OHM 1/8W JUMP 0805 SMD	Panasonic Electronic Components	ERJ-6GEY0R00V	P0.0ACT-ND
11	1	34.0k	R3A	RES, 34k ohm, 0.1%, 0.125W, 0805 SMD	Panasonic Electronic Components	ERA-6AEB3402V	P34KDATR-ND
12	2	620 ohm	R3B, R6B	RES, 620 ohm, 0.1%, 0.125W, 0805 SMD	Panasonic Electronic Components	ERA-6AEB621V	P620DATR-ND
13	1	34.0k	R6A	RES, 34k ohm, 0.1%, 0.125W, 0805 SMD	Panasonic Electronic Components	ERA-6AEB3402V	P34KDATR-ND
14	1	100k	R10	RES, 100k ohm, 5%, 0.125W, 0805	Vishay Dale	CRCW0805100KJNEA	541-100KACT-ND
15	1	1x2	SH-1	Shunt, 100mil, Flash Gold, Black	Sullins Connector Solutions	SPC02SYAN	S9001-ND
16	4		TP +In, TP -In, TP Out, TP V2	TEST POINT - RED	Keystone Electronics	5005	5005K-ND
17	1		U1	40-ns, microPOWER, Push-Pull Output Comparator	Texas Instruments	TLV3201AIDBVR	296-36750-1-ND

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